

**PROCESSING METHOD OF WAFER, PROTECTIVE SHEET, AND
PROTECTIVE SHEET LAYING METHOD**

ABSTRACT

There is provided a processing method of a wafer. The processing method includes a protective sheet preparation step of preparing a protective sheet including a first sheet that is thermocompression-bonded to a surface of the wafer by heating, a second sheet that is laid on the first sheet and has fluidity due to the heating, and a third sheet that is laid on the second sheet and keeps flatness even with the heating. The processing method also includes protective sheet laying step of causing a side of the first sheet to face a front surface of the wafer and executing heating to execute thermocompression bonding to lay the protective sheet on the front surface of the wafer and a grinding step of causing a side of the protective sheet to be held by a holding surface.

[Fig. 3A]